

# LEADTEK

# GPS

Global  
Positioning  
System



## LR9552 GPS Module



|  |                  |
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# 1. Introduction

The Leadtek GPS 9952 module (LR9552) is a high sensitivity and very compact smart antenna module, with built in GPS receiver circuit. This 20-channel global positioning system (GPS) receiver is designed for a wide range of OEM applications and is based on the fast and deep GPS signal search capabilities of SiRFStarIII™ architecture. Leadtek GPS 9552 is designed to allow quick and easy integration into GPS-related applications such as:

- λ PDA, Pocket PC, and other computing devices
- λ Car and Marine Navigation
- λ Fleet Management /Asset Tracking
- λ AVL and Location-Based Services
- λ Hand-Held Device for Personal Positioning and Navigation

## 1.1. Features

### Hardware and Software

- λ Based on the high performance features of the SiRF GSC3f/LP single chip
- λ Compact module size for easy integration: 25 x 25 x 8.9 mm (with 4 mm patch antenna)  
25 x 25 x 6.9 mm (with 2 mm patch antenna) **[option]**
- λ Fully automatic assembly: reflow solder assembly ready
- λ Hardware compatible with SiRF GSW3.2 serial software

### Performance

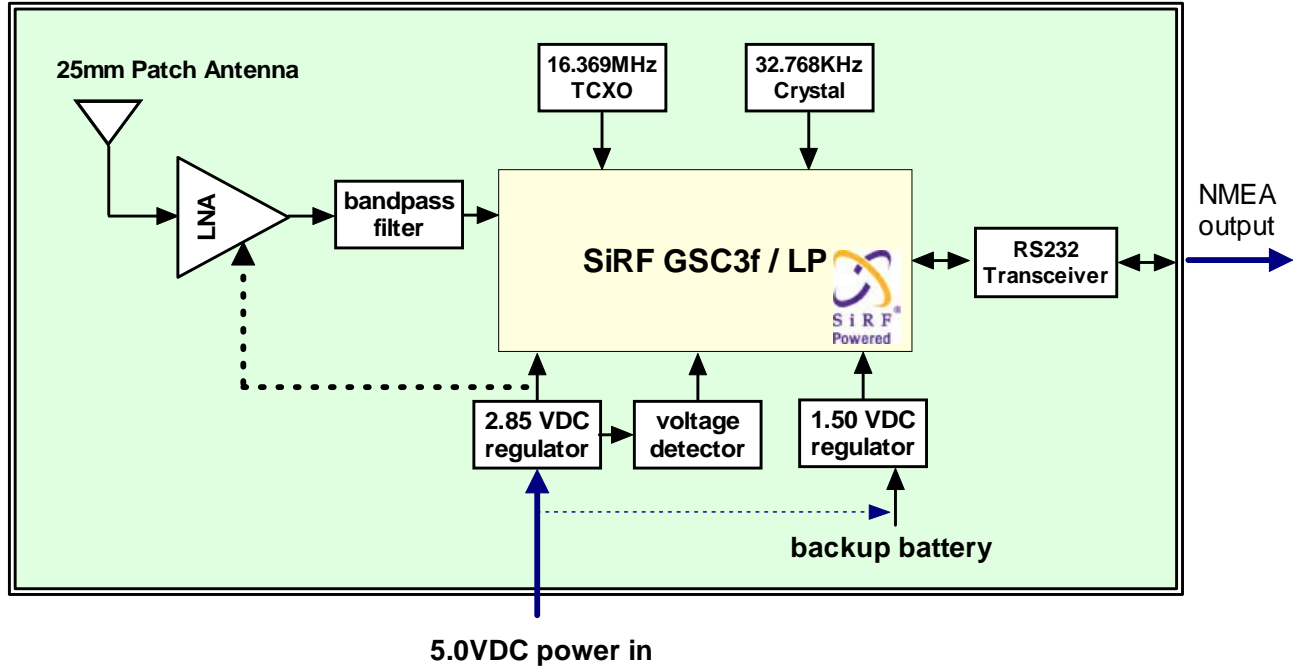
- λ Cold/Warm/Hot Start Time: 42/38/1 sec.
- λ Reacquisition Time: 0.1 second.
- λ RF Metal Shield for best performance in noisy environments.

### Interface

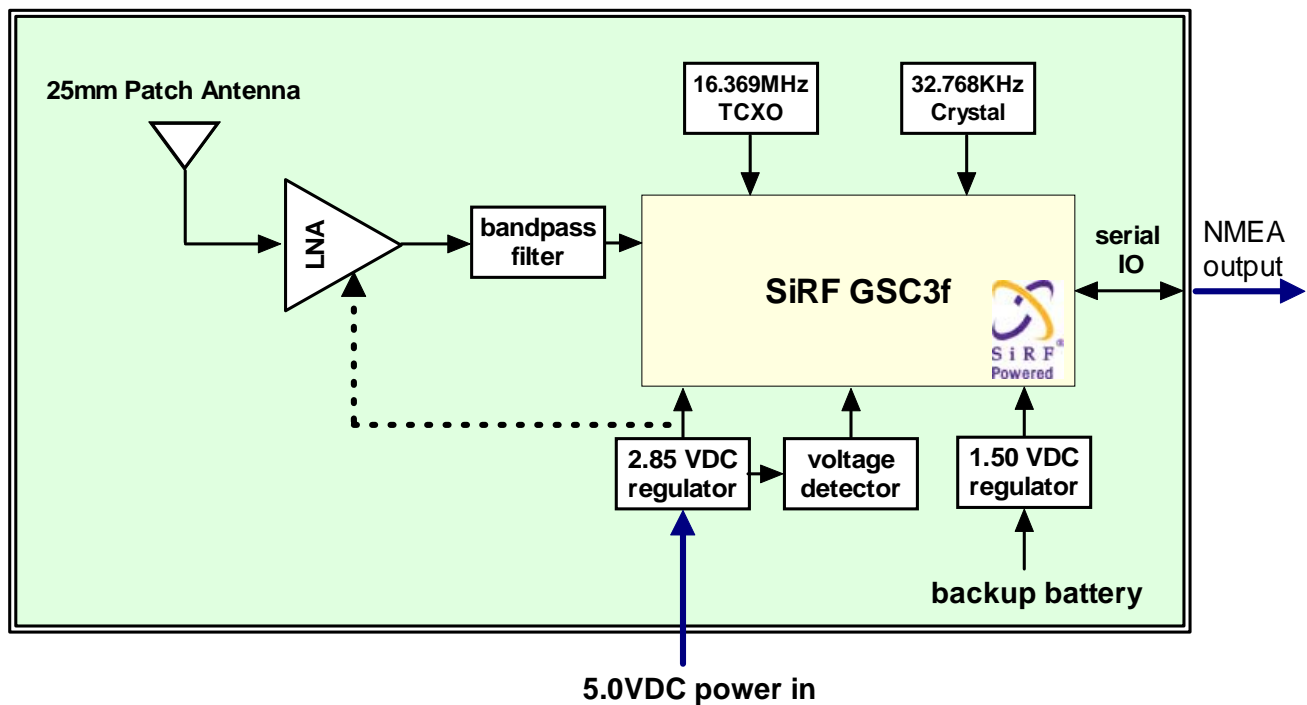
- λ RS232 or TTL (**option**) level serial port for GPS communications interface
- λ Protocol: NMEA-0183/SiRF Binary (default NMEA).
- λ Baud Rate: 4800 ~ 57600 baud (default 4800).

## 2. Module architecture

LR9552 ( RS232 ) Block Diagram



9552 ( TTL ) Block Diagram



## 2.1. Dimensions

The Physical dimensions of the Leadtek 9552 GPS Module are as follow:

| Items  | Description   |
|--------|---|
| Length | 25.0 ± 0.3 mm   |
| Width  | 25.0 ± 0.3 mm   |
| Height | 8.90 ± 0.3 mm<br>6.90 ± 0.3 mm                              |
| Weight | 13.0g (w/ 4mm patch antenna)<br>8.0g (w/ 2mm patch antenna) |

## 2.2. Software Features

The Leadtek 9552 module includes GSW3.2., high sensitivity software solution. For SiRFStarIII/LP receivers, the default configuration is as follows:

| Item             | Description   |
|------------------|---|
| Core of firmware | SiRF GSW3.2   |
| Baud rate        | 4800, 9600, 19200, 38400 or 57600 bps (default 4800)  |
| Code type        | NMEA-0183 ASCII                                       |
| Datum            | WGS-84  |
| Protocol message | GGA(1sec), GSA(5sec), GSV(5sec), RMC(1sec), VTG(1sec) |
| Output frequency | 1 Hz  |

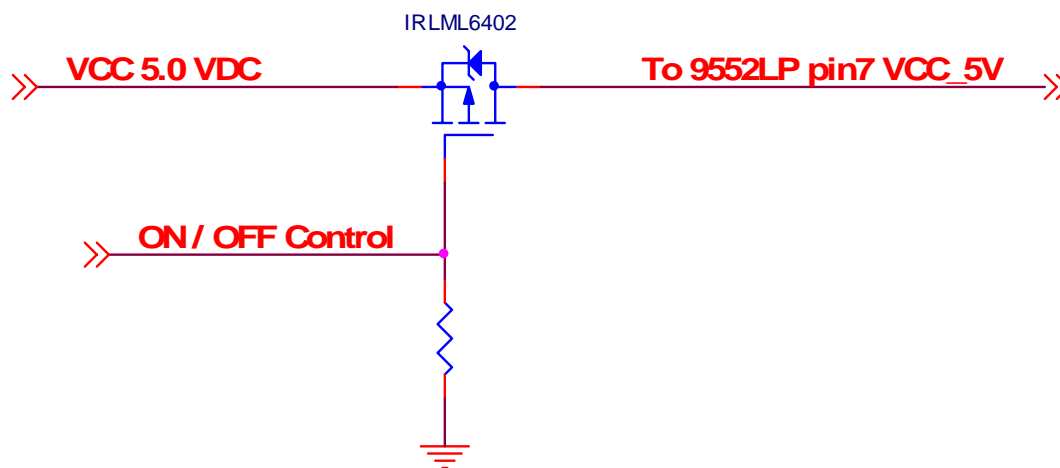
## 2.3. Environmental Specification

| Item                              | Description  |
|-----------------------------------|--|
| Operating temperature rang (note) | -30 deg. C to +60 deg. C   |
| Storage temperature range         | -30 deg. C to +65 deg. C   |
| Humidity                          | up to 95% non-condensing or a wet bulb temperature of +35 deg. C |
| Altitude                          | 18,000 meters (60,000 feet) max.                                 |
| Velocity                          | 515 meters/second (1000 knots) max.                              |
| Jerk                              | 20 meters/second <sup>3</sup> , max.                             |
| Acceleration                      | 4g, max.   |

*Note: The module can be operated between -30°C ~ +85°C, but higher temperature may cause internal Li backup battery deterioration that will influence the performance of GPS hot start.*


## 2.4. Reference design

The user can use a PMOS to control 9552 power on or off as below:



## 2.5. Regulations compliance

**RoHS:** This device complies with the Restriction of Hazardous Substances (RoHS) directive that is enforced on 1st July 2006, saying all electronic products sold in the EU must with RoHS compliance.

| Intertek Labtest  |   | Intertek Labtest   |  | Intertek Labtest    |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
|---|---|--|--|---------------------|--------------|-------------------------|----|----------------------------|----|----------------------------|----|---|----|-------------------|----|--------------|----------------|-----------------|----------------------------|--|-------|-------------------------|--|-------|----------------------------|--|-------|---|---|-------|-------------------|---|-------|---|--|
| TEST REPORT   |   | TEST REPORT  |  | TEST REPORT         |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| NUMBER : TR20027684   |   | NUMBER : TR20027684  |  | NUMBER : TR20027684 |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| <p>APPLICANT: LEADTEK RESEARCH INC.<br/>4F NO. 1, TAIPEI SUB CITY<br/>SHONGHAI RD SHONGHAI CITY<br/>TAIPEI 10001 TAIWAN</p> <p>DATE : AUG 15, 2006</p> <p>TEST DESCRIPTION:<br/>QSG (2) GROUP OF SUBMITTED SAMPLES SAID TO BE :<br/>SAMPLE DESCRIPTION : QSG 9552 PCB<br/>ITEM NO. : QSG 9552<br/>DATE SAMPLE RECEIVED : AUG 14, 2006<br/>DATE TEST STARTED : AUG 14, 2006<br/>REMARKS:</p> <p>TEST METHOD:<br/>AS REQUESTED BY THE APPLICANT, FOR DETAILS PLEASE REFER TO ATTACHED PAGES.</p> <p>AUTHORIZED BY:<br/>CHIEF OF INTERTEK TESTING SERVICES<br/>TAINAN LIMITED</p> <p>JACOB LIN<br/>GENERAL MANAGER</p> |   | <p>TEST CONDUCTED</p> <p>(A) TEST RESULT SUMMARY</p> <table border="1"> <thead> <tr> <th>TESTING ITEM</th> <th>RESULT (ppm)</th> </tr> </thead> <tbody> <tr> <td>LEAD (Pb) CONTENT / 鉛含量</td> <td>ND</td> </tr> <tr> <td>CADMIUM (Cd) CONTENT / 鎘含量</td> <td>ND</td> </tr> <tr> <td>MERCURY (Hg) CONTENT / 汞含量</td> <td>ND</td> </tr> <tr> <td>CHROMIUM VI (Cr<sup>VI</sup>) CONTENT / 六價鉻含量</td> <td>ND</td> </tr> <tr> <td>PBSA/PBDB / 多環芳烴類</td> <td>ND</td> </tr> </tbody> </table> <p>REMARKS : ppm = PARTS PER MILLION<br/>ND = NOT DETECTED<br/>SAMPLES WERE GROUND AND RANDOMLY SELECTED FOR TEST</p> <p>(B) TEST METHOD</p> <table border="1"> <thead> <tr> <th>TESTING ITEM</th> <th>TESTING METHOD</th> <th>REPORTING LIMIT</th> </tr> </thead> <tbody> <tr> <td>CADMIUM (Cd) CONTENT / 鎘含量</td> <td>WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES</td> <td>2 ppm</td> </tr> <tr> <td>LEAD (Pb) CONTENT / 鉛含量</td> <td>WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES</td> <td>2 ppm</td> </tr> <tr> <td>MERCURY (Hg) CONTENT / 汞含量</td> <td>WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES</td> <td>2 ppm</td> </tr> <tr> <td>CHROMIUM VI (Cr<sup>VI</sup>) CONTENT / 六價鉻含量</td> <td>WITH REFERENCE TO USEPA 1631 &amp; 1631A, BY ALKALINE DISSOLUTION AND DETERMINED BY TOXIC</td> <td>2 ppm</td> </tr> <tr> <td>PBSA/PBDB / 多環芳烴類</td> <td>WITH REFERENCE TO USEPA 1631C, BY SOLVENT EXTRACTION AND DETERMINED BY GC-MSD OR HPLC-DAD</td> <td>5 ppm</td> </tr> </tbody> </table> <p>REMARKS : REPORTING LIMIT = QUANTIFICATION LIMIT OF ANALYTE IN SAMPLE</p> |  | TESTING ITEM        | RESULT (ppm) | LEAD (Pb) CONTENT / 鉛含量 | ND | CADMIUM (Cd) CONTENT / 鎘含量 | ND | MERCURY (Hg) CONTENT / 汞含量 | ND | CHROMIUM VI (Cr <sup>VI</sup> ) CONTENT / 六價鉻含量 | ND | PBSA/PBDB / 多環芳烴類 | ND | TESTING ITEM | TESTING METHOD | REPORTING LIMIT | CADMIUM (Cd) CONTENT / 鎘含量 | WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES | 2 ppm | LEAD (Pb) CONTENT / 鉛含量 | WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES | 2 ppm | MERCURY (Hg) CONTENT / 汞含量 | WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES | 2 ppm | CHROMIUM VI (Cr <sup>VI</sup> ) CONTENT / 六價鉻含量 | WITH REFERENCE TO USEPA 1631 & 1631A, BY ALKALINE DISSOLUTION AND DETERMINED BY TOXIC | 2 ppm | PBSA/PBDB / 多環芳烴類 | WITH REFERENCE TO USEPA 1631C, BY SOLVENT EXTRACTION AND DETERMINED BY GC-MSD OR HPLC-DAD | 5 ppm | <p>TEST CONDUCTED</p> <p>PHOTO</p>  <p>Intertek Testing Services Taiwan Ltd.<br/>No. 421, Hsinchu Road, Hsinchu City, Taiwan, R.O.C.<br/>Tel: (886) 3 591 2000 Fax: (886) 3 591 2001</p> |  |
| TESTING ITEM  | RESULT (ppm)  |  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| LEAD (Pb) CONTENT / 鉛含量   | ND  |  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| CADMIUM (Cd) CONTENT / 鎘含量  | ND  |  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| MERCURY (Hg) CONTENT / 汞含量  | ND  |  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| CHROMIUM VI (Cr <sup>VI</sup> ) CONTENT / 六價鉻含量   | ND  |  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| PBSA/PBDB / 多環芳烴類   | ND  |  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| TESTING ITEM  | TESTING METHOD  | REPORTING LIMIT  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| CADMIUM (Cd) CONTENT / 鎘含量  | WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES          | 2 ppm  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| LEAD (Pb) CONTENT / 鉛含量   | WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES          | 2 ppm  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| MERCURY (Hg) CONTENT / 汞含量  | WITH REFERENCE TO USEPA 1631, BY MICROWAVE DISSOLUTION AND DETERMINED BY ICP-OES          | 2 ppm  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| CHROMIUM VI (Cr <sup>VI</sup> ) CONTENT / 六價鉻含量   | WITH REFERENCE TO USEPA 1631 & 1631A, BY ALKALINE DISSOLUTION AND DETERMINED BY TOXIC     | 2 ppm  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |
| PBSA/PBDB / 多環芳烴類   | WITH REFERENCE TO USEPA 1631C, BY SOLVENT EXTRACTION AND DETERMINED BY GC-MSD OR HPLC-DAD | 5 ppm  |  |                     |              |                         |    |                            |    |                            |    |   |    |                   |    |              |                |                 |                            |  |       |                         |  |       |                            |  |       |   |   |       |                   |   |       |   |  |

**FCC/CE:** This device complies with the Federal Communications Commission (FCC), an independent United States government agency regulating interstate and international communications by radio, television, wire, satellite and cable, and CE, an European electromagnetic waves emission and immunity party, regulations.

**DECLARATION OF CONFORMITY**

**FCC**

**Responsible Party Name :** Leadtek Research Inc.  
**Address :** 18F, No. 166, Chien-Yi Rd., Chung-Ho, Taipei Hsien, Taiwan, (235) R.O.C.  
**Phone / Fax No :** 866-2-82265800 / 866-2-82265801

**Trade Name :** LEADTEK  
**Product Name :** GPS 9552 SIRF STAR III SINGLE CHIP  
**Model Number :** LR9552

**Conforms to the following specifications:**  
 CFR 47, FCC Part 15 and DISPER 22, Subpart B, Section 15.107(a) and Section 15.109(a), Class B Digital Device

**Supplementary Information:**  
 This device complies with the Part 15 of the FCC Rules. Operation is Subject to the following two conditions: (1) This device may not cause harmful interference, and (2) This device must accept any interference received, including interference that may cause undesired operation.

**Authorized Representation :** KAL C.T. HUANG  
**Signature :** [Signature]  
**Date :** 2006-08-15

**VERIFICATION OF COMPLIANCE**

**FC**

*This Verification of Compliance is hereby issued to the below named company. The test results of this report relate only to the tested sample identified in this report.*

**Technical Standard:** FCC Part 15 Class B (DnC)  
 IC ICES-003  
*(Operator's Limitations: Part Home and Office Use)*

**General Information**  
**Applicant:** Leadtek Research Inc.  
 18F, No. 166, Chien-Yi Rd., Chung-Ho, Taipei Hsien, Taiwan, (235) R.O.C.

**Product Description**  
**EUT Description:** GPS 9552 SIRF STAR III SINGLE CHIP  
**Trade Name:** LEADTEK  
**Model Number:** LR9552

**Measurement Facilities**  
**Laboratory Name:** Compliance Certification Services Inc.  
 No. 165, Chung Sheng Road, Hsin-Tsuen City, Taipei, Taiwan, P.O.C.  
 Tel: +886-2-22170894 Fax: +886-2-22171029

*This device has been shown to be in compliance with and was tested in accordance with the measurement procedures specified in the Standards & Specifications listed above and as indicated in the measurement report number: 60803201-D*

**Vince Chiang / Assistant Manager**  
 Date: August 10, 2006

**VERIFICATION OF COMPLIANCE**

**CE**

*This Verification of Compliance is hereby issued to the below named company. The test results of this report relate only to the tested sample identified in this report.*

**Technical Standard:** EMC DIRECTIVE 89/336/EEC  
 (EN55022 / EN55024)  
*(Operation Environment: Information Technology Equipment)*

**General Information**  
**Applicant:** Leadtek Research Inc.  
 18F, No. 166, Chien-Yi Rd., Chung-Ho, Taipei Hsien, Taiwan, (235) R.O.C.

**Product Description**  
**EUT Description:** GPS 9552 SIRF STAR III SINGLE CHIP  
**Trade Name:** LEADTEK  
**Model Number:** LR9552

**Measurement Standard**  
 EN 55022: 1998 + A1: 2000 + A2: 2003  
 EN 61000-3-2: 2000  
 EN 61000-3-3: 1995 + A1: 2001  
 EN 55024: 1998 + A1: 2001 + A2: 2003  
 IEC 61000-4-2: 1995 + A1: 1998 + A2: 2000; IEC 61000-4-3: 2002 + A1: 2002;  
 IEC 61000-4-4: 1995 + A1: 2000 + A2: 2001; IEC 61000-4-5: 1993 + A1: 2000;  
 IEC 61000-4-6: 1996 + A1: 2000; IEC 61000-4-8: 1993 + A1: 2000; IEC 61000-4-11: 1994 + A1: 2000

**Measurement Facilities**  
**Laboratory Name:** Compliance Certification Services Inc.  
 No. 165, Chung Sheng Road, Hsin-Tsuen City, Taipei, Taiwan, P.O.C.  
 Tel: +886-2-22170894 Fax: +886-2-22171029

*This device has been shown to be in compliance with and was tested in accordance with the measurement procedures specified in the Standards & Specifications listed above and as indicated in the measurement report number: 60803201-E*

**Vince Chiang / Assistant Manager**  
 Date: August 10, 2006

**EC-Declaration of Conformity**

**CE**

For the following equipment:  
 GPS 9552 SIRF STAR III SINGLE CHIP  
 (Product Name)  
 LR9552 / LEADTEK  
 (Model Designation / Trade Name)  
 Leadtek Research Inc.  
 (Manufacturer Name)  
 3F, No. 4, Alley 11, Lane 327, Sec. 2, Chung Shan Rd.,  
 Chung Ho, Taipei Hsien, Taiwan, R. O. C.  
 (Manufacturer Address)

is herewith confirmed to comply with the requirements set out in the Council Directive on the Approximation of the Laws of the Member States relating to Electromagnetic Compatibility Directive (89/336/EEC, Amended by 92/31/EEC, 93/68/EEC & 98/13/EC). For the evaluation regarding the Electromagnetic Compatibility (89/336/EEC, Amended by 92/31/EEC, 93/68/EEC & 98/13/EC), the following standards are applied:

☒ EN 55022: 1998 + A1: 2000 + A2: 2003  
☒ EN 61000-3-2: 2000  
☒ EN 61000-3-3: 1995 + A1: 2001  
☒ EN 55024: 1998 + A1: 2001 + A2: 2003  
 IEC 61000-4-2: 1995 + A1: 1998 + A2: 2000;  
 IEC 61000-4-3: 2002 + A1: 2002;  
 IEC 61000-4-4: 1995 + A1: 2000 + A2: 2001;  
 IEC 61000-4-5: 1995 + A1: 2000; IEC 61000-4-6: 1996 + A1: 2000;  
 IEC 61000-4-8: 1993 + A1: 2000; IEC 61000-4-11: 1994 + A1: 2000

The following manufacturer / importer or authorized representative established within the EUT is responsible for this declaration:  
 Leadtek Research Inc.  
 (Company Name)  
 18F, No. 166, Chien Yi Rd., Chung Ho, Taipei Hsien, Taiwan, (235) R.O.C.  
 (Company Address)

Person responsible for making this declaration:  
 (Name, Surname) KAL C.T. HUANG  
 (Position / Title) DEPUTY CHIEF ENGINEER  
 (Place) 2006-08-15 (Date) [Signature] (Legal Signature)

Please note that the compliances of this device are for this SMD module itself only. The complete system compliance must be examined and certified whenever you put this SMD inside.



### 3. Performance Characteristics

#### 3.1. Position and velocity accuracy

|                 |          |  |
|-----------------|----------|--|
| <b>Accuracy</b> | Position | 10 meters, 2D RMS<br>5 meters 2D RMS, WAAS corrected<br><5meters(50%). |
|                 | Velocity | 0.1 meters/second  |
|                 | Time     | 1 microsecond synchronized to GPS time                                 |

#### 3.2. Dynamic constrains

|                           |              |                                      |
|---------------------------|--------------|--------------------------------------|
| <b>Dynamic Conditions</b> | Altitude     | 18,000 meters (60,000 feet) max.     |
|                           | Velocity     | 515 meters/second (1000 knots) max.  |
|                           | Acceleration | 4g, max.                             |
|                           | Jerk         | 20 meters/second <sup>3</sup> , max. |

#### 3.3. Acquisition time <sup>1</sup>

| Mode   | Leadtek 9552 GPS Module |
|--|-------------------------|
| TTFF Hot<br>(valid almanac, position, time & ephemeris)                              | 1 s                     |
| TTFF Warm<br>(valid almanac, position, & time)                                       | 38 s                    |
| TTFF Cold<br>(valid almanac)   | 42 s                    |
| re-acquisition<br>(<10 s obstruction with valid almanac, position, time & ephemeris) | 100 ms                  |

**Note 1: Open Sky and Stationary Environments.**

### 3.4. Timing 1PPS output

The 1PPS pulse width is 1  $\mu$ s, this 1PPS is NOT suited to steer various oscillators (timing receivers, telecommunications system, etc).

### 3.5. Sensitivity

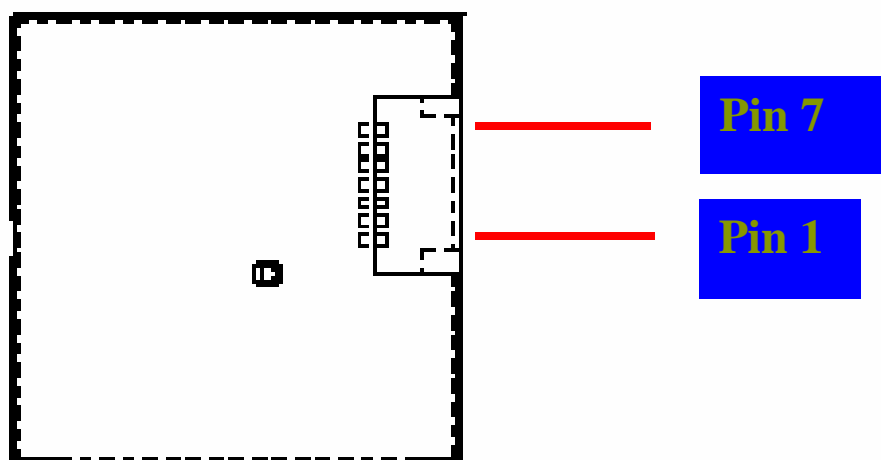
| Parameter               | Description |
|-------------------------|-------------|
| Tracking Sensitivity    | -158 dBm    |
| Acquisition Sensitivity | -142 dBm    |

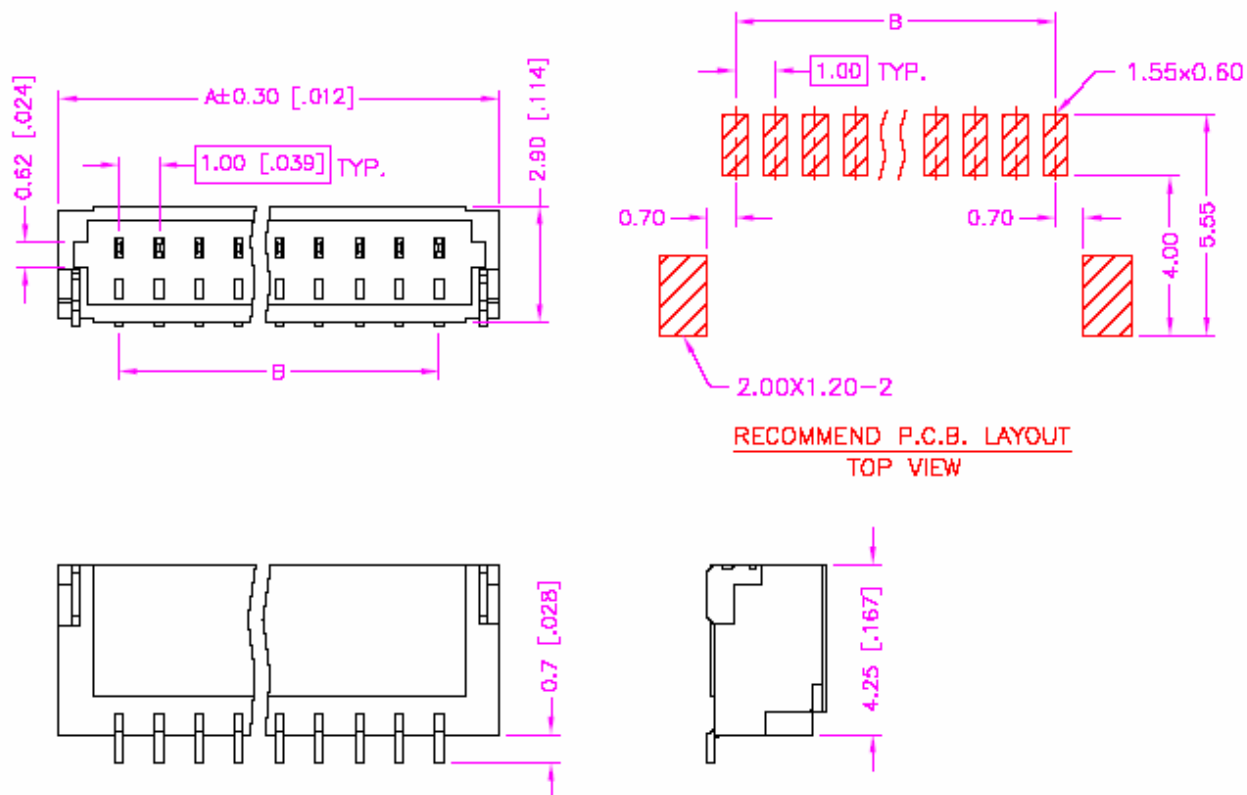
## 4. Hardware Interface Power supply

| Parameter                          | Leadtek 9552 GPS Module |
|------------------------------------|-------------------------|
| Input voltage                      | 3.2 ~ 5.0V DC input.    |
| Current (typ) at full power (3.3V) | 55mA                    |
| Battery backup voltage             | 1.65 ~ 5.0V DC input.   |

### 4.1. Specifications

#### I.Pin Positions





## II. Pin Assignment

| Pin No. | Define | Pin No. | Define   |
|---------|--------|---------|----------|
| 1       | GND    | 5       | RXDB     |
| 2       | TXDA   | 6       | TIMEMARK |
| 3       | RXDA   | 7       | VCC_5V   |
| 4       | TXDB   |         |          |

## 5. Software interface

The host serial I/O port of the module's serial data interface supports full duplex communication between the module and the user. The default serials are shown in Table 5-1.

| Port   | Protocol            | Description                  |
|--------|---------------------|------------------------------|
| Port A | NMEA 0183, 9600 bps | GGA, GSA, GSV, GLL, RMC, VTG |
| Port B | N/A                 | N/A                          |

Table 5-1 Leadtek 9552 GPS module default baud rates

The Leadtek LR9552 module includes GSW3 high sensitivity software solution.

Features include:

- λ High tracking sensitivity
- λ High configurability
- λ 1 Hz position update rate
- λ Real-time Operating System (RTOS) friendly
- λ Capable of outputting both NMEA and SiRF-proprietary binary protocols
- λ Designed to accept custom user tasks executed on the integrated ARM7TDM1 processor
- λ Runs in full power operation or optional power saving modes

GSW3 default configuration is as follows:

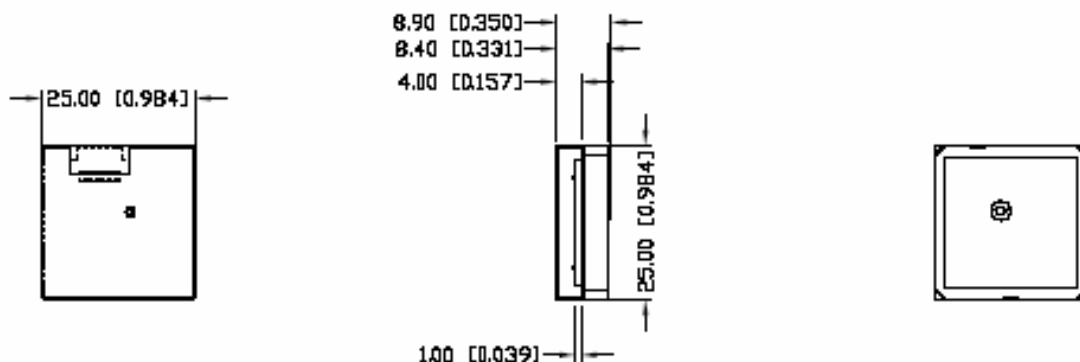
| Item                    | Description   |
|-------------------------|---|
| <b>Core of firmware</b> | GSW3.2 serial   |
| <b>Baud rate</b>        | 4800, 9600, 19200, 38400 or 57600 bps (default 4800)  |
| <b>Code type</b>        | NMEA-0183 ASCII                                       |
| <b>Datum</b>            | WGS-84  |
| <b>Protocol message</b> | GGA(1sec), GSA(5sec), GSV(5sec), RMC(1sec), VTG(1sec) |
| <b>Output frequency</b> | 1 Hz  |

## 6. Mechanical drawing and footprint

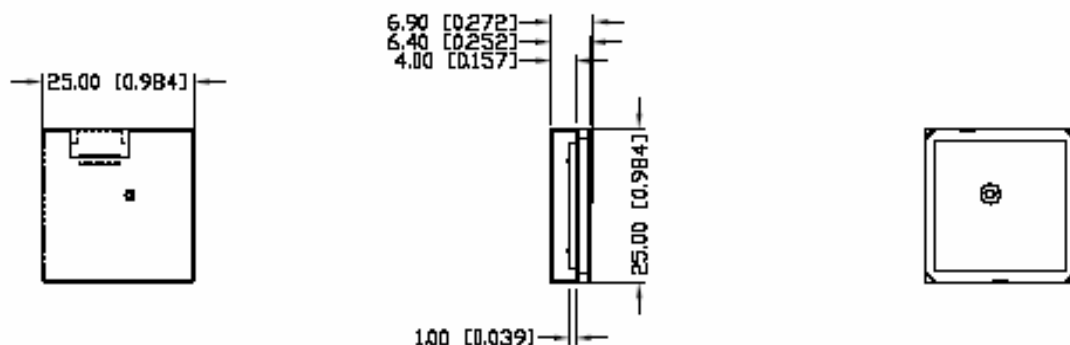
### 6.1. Outline Drawing

| Items  | Description                    |
|--------|--------------------------------|
| Length | 25.0 ± 0.3 mm                  |
| Width  | 24.0 ± 0.3 mm                  |
| Height | 8.90 ± 0.3 mm<br>6.90 ± 0.3 mm |

(4mm patch antenna)



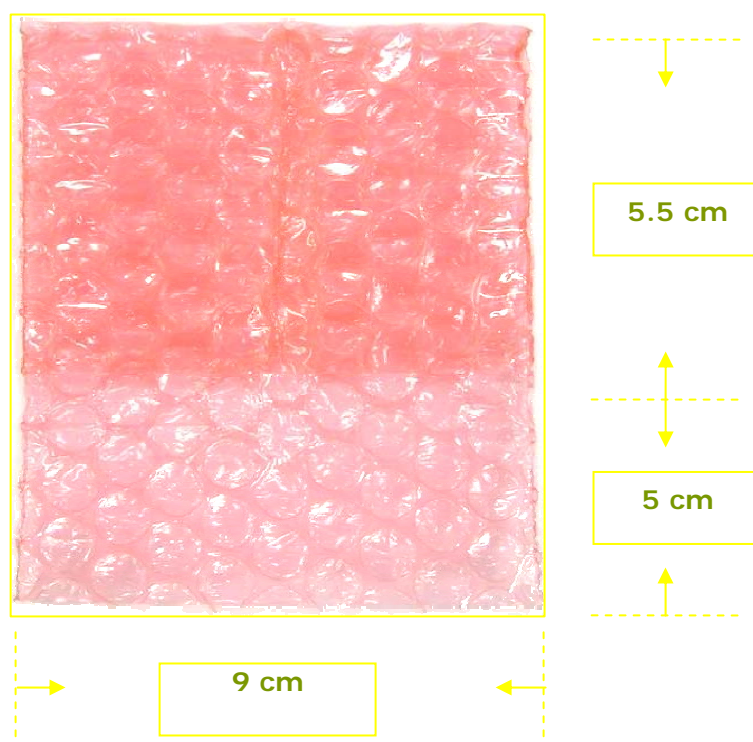
(2mm patch antenna)



## 7. Package

### 7.1. Package specifications

*Tolerance:  $\pm 10\text{mm}$*



- λ Electric Specification: Surface impedance
- λ Relative humidity: 50%
- λ Relative temperature: 24°C ~ 28°C
- λ Bubble diameter: 1cm
- λ Color: pink
- λ With SGS Test Report
- λ Dimension: 90mm(W) x 55mm + 50mm (L)

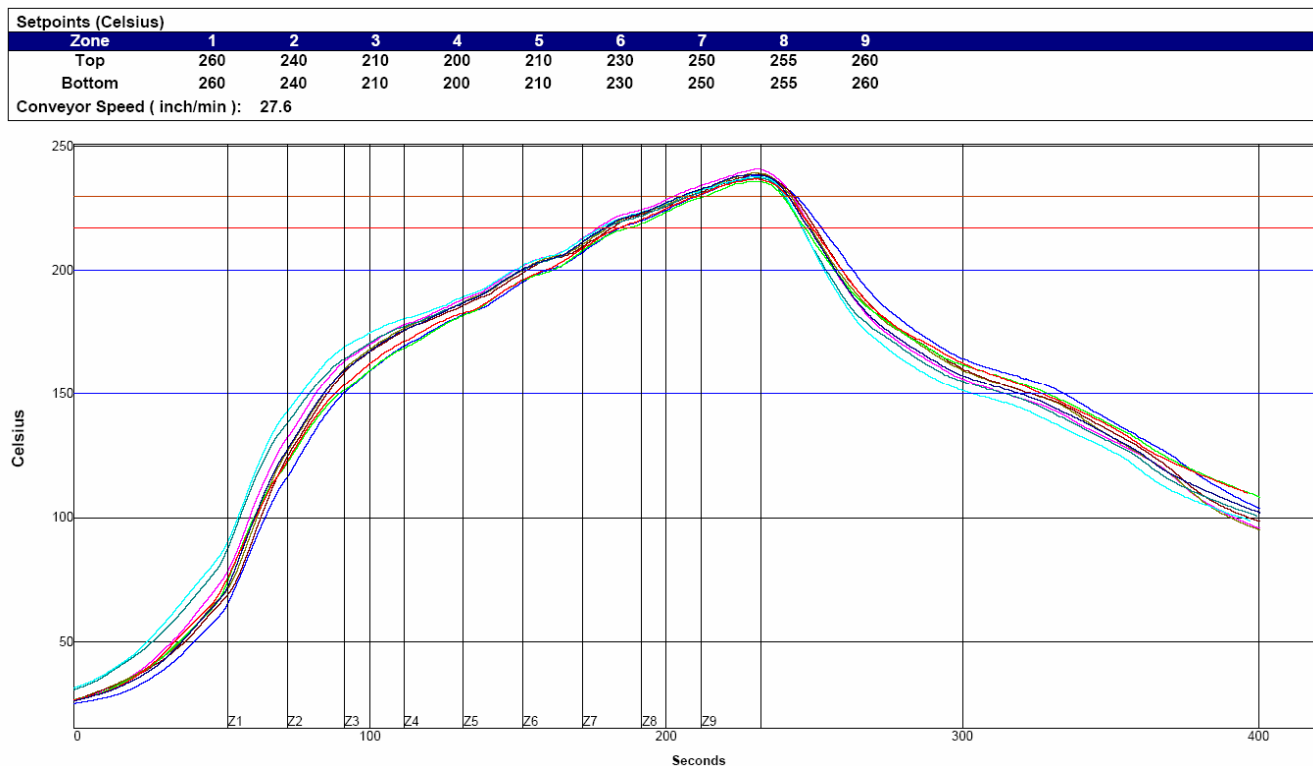
## 8. RoHS compliant information

By July 1, 2006, all electronic products sold in the EU must be free of hazardous materials, such as lead. Leadtek is fully committed to being one of the first to introduce lead-free GPS Products while maintaining backwards compatibility and focusing on a continuously high level of product and manufacturing quality.

### 8.1. RoHS soldering profile

#### *Reflow Profile*

High quality, low defect soldering requires identifying the optimum temperature profile for reflowing the solder paste. To have the correct profile assures components, boards, and solder joints are not damaged and reliable solder connection is achievable. Profiles are essential for establishing and maintaining processes. You must be able to repeat the profile to achieve process consistency. The heating and cooling rise rates must be compatible with the solder paste and components. The amount of time that the assembly is exposed to certain temperatures must first be defined and then maintained. The following is an example of a typical thermal profile.





# Glossary

## A-GPS

Assisted GPS or AGPS is a technology that uses an assistance server to cut down the time needed to find the location. Although GPS provides excellent position accuracy, position fixes require lines of sight to the satellites. In regular GPS networks there are only GPS satellites and GPS receivers. In A-GPS networks, the receiver, being limited in processing power and normally under less than ideal locations for position fixing, communicates with the assistance server that has high processing power and access to a reference network. Although dependent on cellular coverage, AGPS processing is quicker and more efficient than regular GPS.

## API

An application programming interface is a set of definitions of the way one piece of computer software communicates with another. One of the primary purposes of an API is to provide a set of commonly used functions, such as to draw windows or icons on the screen. Programmers can then take advantage of the API by making use of its functionality, saving them the task of programming everything from scratch.

## Baud Rate

Is a measure of the signaling rate, which is the number of changes to the transmission media per second in a modulated signal.

For Example: 250 baud means that 250 signals are transmitted in one second. If each signal carries 4 bits of information then in each second 1000 bits are transmitted. This is abbreviated as 1000 bit/s.

## Dead Reckoning

The process of estimating your position by advancing a known position using course, speed, time and distance to be traveled. It is figuring out where you will be at a certain time if you hold the speed, time and course you plan to travel.

## Differential GPS (DGPS)

An extension of the GPS system that uses land-based radio beacons to transmit position corrections to GPS receivers. DGPS reduces the effect of selective availability, propagation delay, etc. and can improve position accuracy to better than 10 meters.

## EGNOS

A satellite navigation system being developed by the European Space Agency, the European Commission, and EUROCONTROL. It is intended to supplement the GPS and GLONASS systems by reporting on the reliability and accuracy of the signals. According to specifications, horizontal position accuracy should be better than 7 meters. In practice, the horizontal position accuracy is at the meter level. It will consist of three geostationary satellites and a network of ground stations.

Similar service is provided in America by the WAAS system. See WAAS.

## **European Geostationary Navigation Overlay System**

See EGNOS.

## **LNA**

A special type of electronic amplifier or amplifier used in communication systems to amplify very weak signals captured by an antenna. It is usually located at the antenna and is a key component, which is placed at the front-end of a receiver system.

## **Low Noise Amplifier**

See LNA.

## **Multi-path mitigation**

Anticipating errors caused when a satellite signal reaches the GPS receiver antenna by more than one path. Usually caused by one or more paths being bounced or reflected off of structures near the antenna and occurs to some extent everywhere. The signal which traverses a longer path will yield a larger pseudo range estimate and increase the error.

## **NMEA**

An U.S. standards committee that defines data message structure, contents, and protocols to allow the GPS receiver to communicate with other pieces of electronic equipment.

## **National Marine Electronics Association**

See NMEA.

## **1PPS**

Pulse which is generated once per second. GPS and some radio clocks and related timekeeping gear have a pulse-per-second or PPS signal that is needed for high accuracy time synchronization. The PPS signal can be connected in either of two ways, either through the data leads of a serial port or through the modem control leads. Either way requires conversion of the PPS signal,

Most GPS devices emit an rs-232 serial stream with some kind of timestamp format. Many GPS devices are small realtime systems with the satellite tracking done at high priority, positioning done at medium priority, and time output done at low priority. The timestamps often have +/- 200 ms of jitter (variance in delay), and output a PPS signal on the exact second.

## **SMD**

Electronic device components that are mounted directly onto the surface of printed circuit boards (PCBs). In the industry it has largely replaced the previous construction method of fitting components with wire leads into holes in the circuit board (also called through-hole technology).

## Surface Mount Device

See SMD.

## TCXO

An electronic device that uses the mechanical resonance of a physical crystal to create an electrical signal with a very precise frequency and can be embedded in integrated circuits. TCXO reduces the environmental changes of temperature, humidity, and vibration, to keep a stable output frequency.

### Temperature Controlled Crystal Oscillator

See TCXO.

## Time To First Fix (TTFF)

The time it takes a GPS receiver to find satellites after you first turn it on, when the GPS receiver has lost memory, or has been moved over 300 miles from its last location. Standard TTFF Timing consists of:

| Mode       | Requires              | Timing         |
|------------|-----------------------|----------------|
| Snap Start | Hot + Clock + Sat Pos | 3 minutes off  |
| Hot Start  | Warm + Ephemeris      | 30 minutes off |
| Warm Start | Position Accuracy     | <500 KM        |
|            | Time Accuracy         | <2 hours       |
|            | Almanac               | <1 year        |
| Cold Start | Nothing               | N/A            |

Specifications are typical times assuming good satellite visibility and above threshold signal strengths.

## WAAS

A system of satellites and ground stations that provide GPS signal corrections for better position accuracy. A WAAS-capable receiver can give you a position accuracy of better than three meters, 95 percent of the time. (At this time, the system is still in the development stage and is not fully operational.) WAAS consists of approximately 25 ground reference stations positioned across the United States that monitor GPS satellite data. Two master stations, located on either coast, collect data from the reference stations and create a GPS correction message.

## Wide Area Augmentation System

See WAAS.



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